



an Open Access Journal by MDPI

Emerging Topics in Integrated Microwave Photonics

Guest Editors:

Dr. Yongsheng Gao

School of Electronics and Information, Northwestern Polytechnical University (NPU), 127 West Youyi Road, Beilin District, Xi'an 710072, China

Dr. Gaojian Liu

Xi'an Institute of Space Radio Technology, No. 504 Chang'an Eastern Street, Xi'an 710100, China

Deadline for manuscript submissions: closed (30 November 2023)



mdpi.com/si/169174

Message from the Guest Editors

Microwave photonic integration is devoted to the research and development of core optical chips and integrated modules for the generation, transmission, processing, and measurement of broadband microwave photonic signals. Microwave photonic integration is the hardware foundation and core technology of the next-generation broadband wireless access network, radar, and electronic countermeasure systems.

Original research articles and comments are welcome. The research fields may include (but are not limited to) the following:

- High-performance III-V family semiconductor optoelectronic integrated devices;
- Optical-electronic hybrid integration technology based on new materials;
- Design and process platform for photoelectronic integrated chips;
- Packaging and testing technology for photoelectronic integrated chips;
- Optical computing and application of quantum information;
- Lidar and sensing applications;
- Data center optical interconnect applications;
- Smart photoelectric application system;
- Memory-computing integrated chip;
- Other interdisciplinary research directions and emerging application technologies.

